

# ChaMP

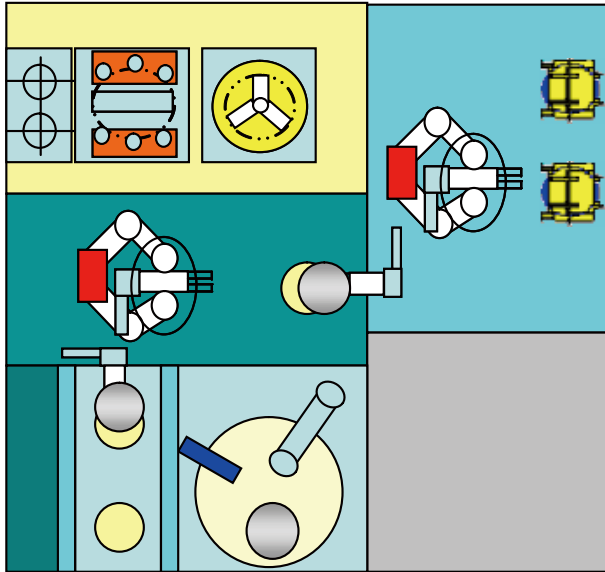
## Chemical Mechanical Planarizers

### Compact CMP System

#### Features

- Reasonable initial cost
- Small footprint
- High performance CMP → Know-how from mass production
- Flexible Customization up to user's requirement
  - From R&D, trial production to mass production
- 2"~8" polishing head available, multiple size of wafers are polishable in one system.
- Mounting of wafer loader enables full-automatic operation
- Mounting of cleaning unit enables precise cleaning





Selectable

[ Specification 1 ]  
Semi-automatic type CMP system

Can be modified

[ Specification 2 ]  
Automatic CMP system with simple loader

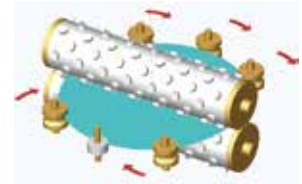
Can be modified

[ Specification 3 ]  
Automatic CMP system with loader & cleaner

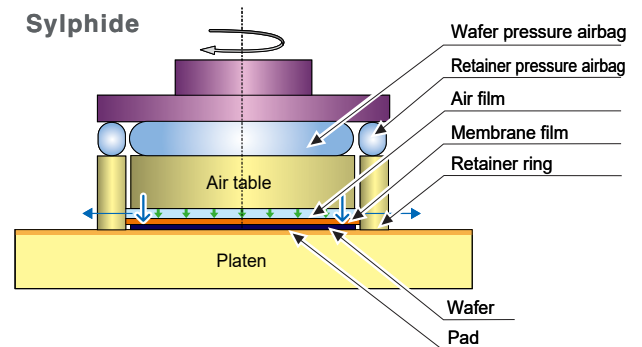
The Cleaner can be separately purchased

## Air-float Head "Sylphide"

- Air film formation provides very **uniform pressure** distribution in the wafer plane.
- Possession of an airbag independent of an air film provides **low-pressure stability**.
- An independent retainer pressure airbag provides excellent **edge profile control**.
- **One-touch replacement** of retainer/membrane reduces downtime (see below).
- Addition of **zone control function** is available (optional).

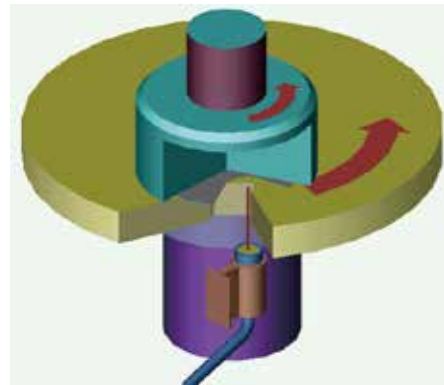
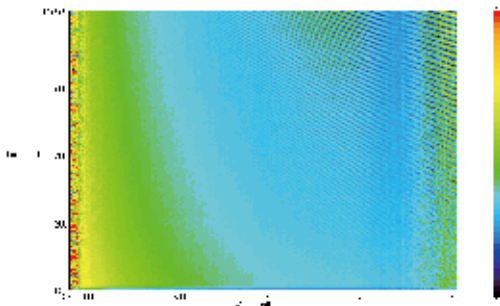


Sylphide



## Optical End-Point Detection System

- Uses white light source and accurately detects residual film changes with reflection data of wide wavelength range and special algorithm.
- Provides a wide range of applications.



Various optional functions for mass production are available.